



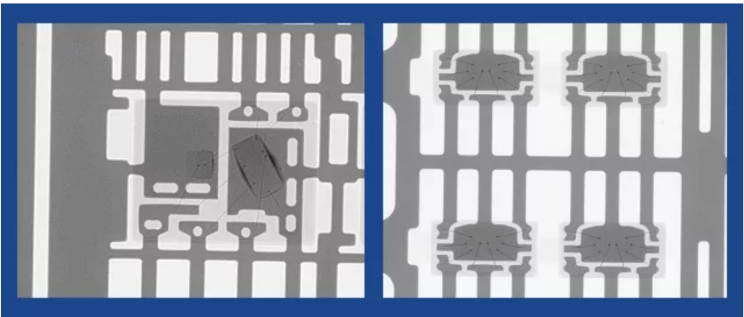
Unicomp AX8300Si

AX8300Si Inline X-ray Inspection Equipment for Semiconductor Lead Structure is an advanced solution designed for the accurate and efficient inspection of semiconductor components. It offers high resolution and internal defect detection capability, ensuring compliance with the required quality standards. With its state-of-the-art technology, the AX8300Si enables detailed, real-time analysis, making it an indispensable tool for manufacturers looking to ensure the integrity and quality of their products, increasing efficiency and productivity on production lines.

Functions and Feature

- Semiconductor, Substrate, Lead Frame & Wire Bonding Inspection
- Package type：W/B,IC,F/C...
- Defect type：Void,Open,Short,Sweep,Solder ball...
- Other areas: Battery, IGBT...

Inspection Image



Detailed Product Description

System Summary	
Footprint	2200(W)×1250(D)×1960(H)mm
Machine Weight	2700 kg
Power Supply	AC 110/220V, 50/60H
Power	6.5 kW
X-Ray Tube	
Tube Type	Seale
Voltage	40~110kV (Adjustable)
Current	200 μA
Focus Spot Size	2 μm
Imaging System	
Detector	Flat Panel Detector (FPD)
Effective Detection Area	116.4*145.7mm
Pixel Matrix	2352*2944
Pixel Size	49.5 μm
Frame Rates	37 fps
Motion Control System	
Movement Control	Keypad & Mouse
Max. Loading Area	310*110mm
Max. Inspection Area	270*100mm
Industrial PC	
Monitor	24" FHD Interactive Touch LCD Display
System OS	Windows 10 64bit
Hard disk	1TB
RAM	8GB
CPU model	Intel i7 Processor
Other Features	
Door Open	Electric Sliding
Authority Management	Fingerprint Access Management System, and Support Password Accessing.
X-Ray Safety	<1μSv/h (Meets All International Standards)
Safety Operation	Electromagnetic Interlock, Warning Light and Real-time Radiation Leakage Monitor
* Specifications are subject to change without notice. All trademarks are the property of the system maker.	

Dimensions

